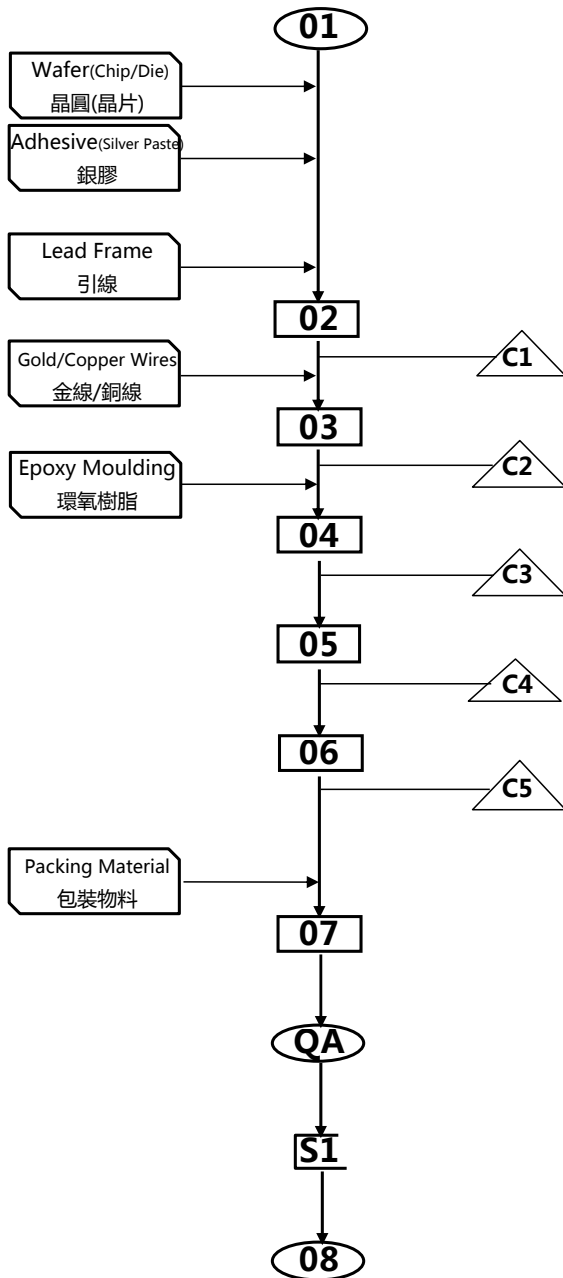


DIODES / TRANSISTORS DIE BONDING 二極管、三極管固晶

PROCESS FLOW CHART FOR ADHESIVE(SILVER PASTE) WIRE BONDING PROCESS PRODUCTS
銀膠焊線工藝產品工序流程圖 (DFN系列)



PROCESS DESCRIPTION

流程說明：

01	MATERIAL INCOMING INSPECTION 來料檢查
02	DIE BONDING 固晶 (晶片焊接)
03	WIRE BONDING 引線鍵合 (焊線焊接)
04	MOULDING 注塑
05	CUTTING & FORMING 切割及成型
06	100% ELECTRICAL TESTING, LASER MARKING & TAPING 100% 電性測試、激光法標記及上帶
07	PACKING 包裝
08	FINAL INSPECTION BEFORE DISPATCHING 交貨前最終檢查
QA	QUALITY ASSURANCE 品質保證檢查
S1	STORAGE 倉儲
C1	QUALITY MONITORING AND CONTROL(IPQC) OF DIE BONDING 晶片焊接過程品質監測及控制
C2	QUALITY MONITORING AND CONTROL(IPQC) OF WIRE BONDING 焊線焊接過程品質監測及控制
C3	QUALITY MONITORING AND CONTROL(IPQC) OF MOULDING 注塑過程品質監測及控制
C4	QUALITY MONITORING AND CONTROL(IPQC) OF CUTTING & FORMING 切割及成型過程品質監測及控制
C5	QUALITY MONITORING AND CONTROL(IPQC) OF TESTING, MARKING & TAPING 測試、標記及上帶過程品質監測及控制

	Operation 操作		Inspection 檢查
	Storage 儲存		Material 材料
	Quality Monitoring and Control 品質監測及控制		